Product/Process Change Notice - PCN 26_0028 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	Qualification of Wafer Fabrication Site Analog Devices Limerick for XF26/XF18/XF12/XF8 Products
Publication Date:	16-Feb-2026
Effectivity Date:	21-May-2026 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release.

Description Of Change:

Qualification of Analog Devices International, Ireland (ADLK) as a wafer fab site for XF26/XF18/XF12/XF8 products.

Reason For Change:

Leveraging the existing qualified process at our Analog Devices Limerick, Ireland Fab ensures a reliable and continuous supply for our customers securing their needs well into the future.

The affected products will be manufactured using ADI specified manufacturing flows, materials, process controls, and monitors ensuring no degradation of quality and reliability performance.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no impact to fit, form, function, or reliability.

Product Identification: *(this section will describe how to identify the changed material)*

Traceability will be maintained via standard ADI lot traceability.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results.

Supporting Documents:

Attachment 1: Type: Delta Qualification Matrix

ADI_PCN_26_0028_Rev_-_PCN-Delta-Qualification-Matrix-ZVEI-5_2_1.xlsm

Attachment 2: Type: Qualification Results Summary

ADI_PCN_26_0028_Rev_-_Qualification_of_ADI_Limerick_Wafer_Fab_XF26_XF18_XF12_XF8_Processes.pdf.pdf

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

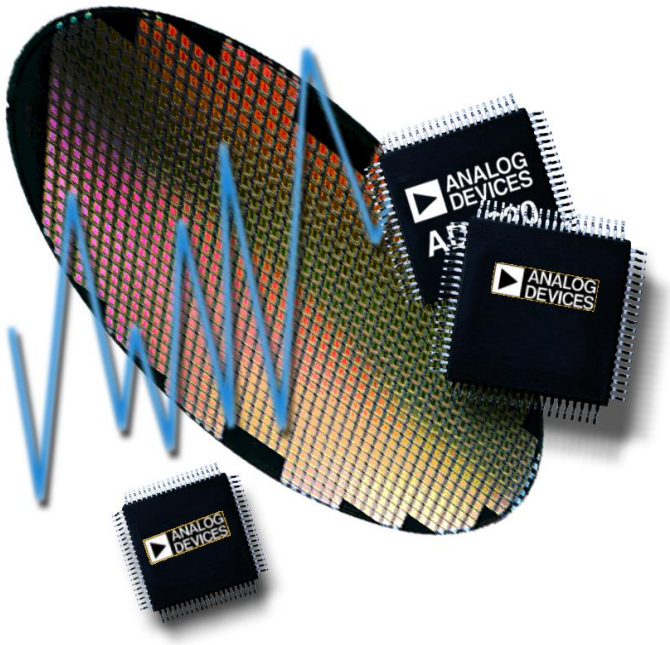
Americas:	Europe:	Japan:	Korea:	Rest of Asia:

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (314)

AD8000 / AD8000YCPZ-REEL
AD8000 / AD8000YCPZ-REEL7
AD8000 / AD8000YRDZ
AD8000 / AD8000YRDZ-REEL7
AD8021 / AD8021ARMZ
AD8021 / AD8021ARMZ-REEL
AD8021 / AD8021ARMZ-REEL7
AD8021 / AD8021ARZ
AD8021 / AD8021ARZ-REEL
AD8021 / AD8021ARZ-REEL7
AD8022 / AD8022ARMZ
AD8022 / AD8022ARMZ-REEL
AD8022 / AD8022ARMZ-REEL7
AD8022 / AD8022ARZ
AD8022 / AD8022ARZ-REEL
AD8022 / AD8022ARZ-REEL7
AD8027 / AD8027ARTZ-R2
AD8027 / AD8027ARTZ-REEL7
AD8027 / AD8027ARZ
AD8027 / AD8027ARZ-REEL
AD8027 / AD8027ARZ-REEL7
AD8027 / ADW13020Z
AD8028 / AD8028-KGD-CHIP
AD8028 / AD8028ARMZ
AD8028 / AD8028ARMZ-REEL7
AD8028 / AD8028ARZ
AD8028 / AD8028ARZ-REEL
AD8028 / AD8028ARZ-REEL7
AD8028 / AD8028WARMZ-R7
AD8029 / AD8029AKSZ-REEL
AD8029 / AD8029AKSZ-REEL7
AD8029 / AD8029ARZ
AD8029 / AD8029ARZ-REEL
AD8029 / AD8029ARZ-REEL7
AD8030 / AD8030ARJZ-REEL7
AD8030 / AD8030ARZ
AD8030 / AD8030ARZ-REEL
AD8030 / AD8030ARZ-REEL7
AD8033 / AD8033AKSZ-REEL7
AD8033 / AD8033ARZ
AD8033 / AD8033ARZ-REEL
AD8033 / AD8033ARZ-REEL7
AD8034 / AD8034ACHIPS
AD8034 / AD8034ARTZ-REEL7
AD8034 / AD8034ARZ
AD8034 / AD8034ARZ-REEL
AD8034 / AD8034ARZ-REEL7
AD8039 / AD8039ARTZ-REEL7
AD8039 / AD8039ARZ
AD8039 / AD8039ARZ-REEL
AD8039 / AD8039ARZ-REEL7
AD8039 / AD8039SRZ-EPR7
AD8040 / AD45092Z
AD8040 / AD8040ARUZ
AD8040 / AD8040ARUZ-REEL7
AD8040 / AD8040ARZ
AD8040 / AD8040ARZ-REEL
AD8040 / AD8040ARZ-REEL7
AD8040 / AD8040WARUZ-REEL7
AD8061 / AD8061ARTZ-REEL
AD8061 / AD8061ARTZ-REEL7
AD8061 / AD8061ARZ
AD8061 / AD8061ARZ-REEL
AD8061 / AD8061ARZ-REEL7
AD8062 / AD8062ARMZ
AD8062 / AD8062ARMZ-R7
AD8062 / AD8062ARMZ-RL
AD8062 / AD8062ARZ
AD8062 / AD8062ARZ-R7
AD8062 / AD8062ARZ-RL
AD8063 / AD8063ARTZ-REEL7
AD8063 / AD8063ARZ
AD8063 / AD8063ARZ-REEL
AD8063 / AD8063ARZ-REEL7
AD8065 / AD8065-KGD-CHIP
AD8065 / AD8065ARTZ-R2
AD8065 / AD8065ARTZ-REEL
AD8065 / AD8065ARTZ-REEL7
AD8065 / AD8065ARZ
AD8065 / AD8065ARZ-REEL
AD8065 / AD8065ARZ-REEL7
AD8065 / AD8065WARTZ-R7
AD8066 / AD8066ARMZ
AD8066 / AD8066ARMZ-REEL7
AD8066 / AD8066ARZ
AD8066 / AD8066ARZ-R7
AD8066 / AD8066ARZ-RL
AD8075 / AD8075ARUZ
AD8075 / AD8075ARUZ-REEL
AD8075 / AD8075ARUZ-REEL7
AD8099 / AD8099ACPZ-REEL
AD8099 / AD8099ACPZ-REEL7
AD8099 / AD8099ARDZ
AD8099 / AD8099ARDZ-REEL
AD8099 / AD8099ARDZ-REEL7
AD8123 / AD8123ACPZ
AD8123 / AD8123ACPZ-R7
AD8123 / AD8123ACPZ-RL
AD8124 / AD8124ACPZ
AD8124 / AD8124ACPZ-R7
AD8124 / AD8124ACPZ-RL
AD8130 / AD45060Z-REEL7
AD8130 / AD8130ACHIPS
AD8130 / AD8130ARMZ
AD8130 / AD8130ARMZ-REEL
AD8130 / AD8130ARMZ-REEL7
AD8130 / AD8130ARZ
AD8130 / AD8130ARZ-REEL
AD8130 / AD8130ARZ-REEL7
AD8131 / AD45059Z-REEL7
AD8131 / AD8131ARMZ
AD8131 / AD8131ARMZ-REEL
AD8131 / AD8131ARMZ-REEL7
AD8131 / AD8131ARZ
AD8131 / AD8131ARZ-REEL
AD8131 / AD8131ARZ-REEL7
AD8132 / AD8132ARMZ
AD8132 / AD8132ARMZ-REEL
AD8132 / AD8132ARMZ-REEL7
AD8132 / AD8132ARZ
AD8132 / AD8132ARZ-R7
AD8132 / AD8132ARZ-RL
AD8132 / AD8132WARMZ-R7
AD8132 / ADW13000Z
AD8133 / AD8133ACPZ-R2
AD8133 / AD8133ACPZ-REEL
AD8133 / AD8133ACPZ-REEL7
AD8137 / AD8137WYCPZ-R7
AD8137 / AD8137YCPZ-REEL7
AD8137 / AD8137YRZ
AD8137 / AD8137YRZ-REEL
AD8137 / AD8137YRZ-REEL7
AD8138 / AD80254
AD8138 / AD8138ACHIPS
AD8138 / AD8138ARMZ
AD8138 / AD8138ARMZ-REEL
AD8138 / AD8138ARMZ-REEL7
AD8138 / AD8138ARZ
AD8138 / AD8138ARZ-R7
AD8138 / AD8138ARZ-RL
AD8138 / AD8138CU-W
AD8138 / AD8138SRMZ-EP-R7
AD8139 / AD8139ACPZ-R2
AD8139 / AD8139ACPZ-REEL
AD8139 / AD8139ACPZ-REEL7
AD8139 / AD8139ARDZ
AD8139 / AD8139ARDZ-REEL
AD8139 / AD8139ARDZ-REEL7
AD8143 / AD8143ACPZ-REEL
AD8143 / AD8143ACPZ-REEL7
AD8145 / AD8145WYCPZ-R7
AD8145 / AD8145YCPZ-R7
AD8145 / AD8145YCPZ-RL
AD8304 / AD8304ARUZ
AD8304 / AD8304ARUZ-RL7
AD8305 / AD8305ACPZ-R2
AD8305 / AD8305ACPZ-RL7
AD8307 / AD8307ANZ
AD8307 / AD8307ARZ
AD8307 / AD8307ARZ-REEL
AD8307 / AD8307ARZ-RL7
AD8310 / AD45240Z
AD8310 / AD45241Z-R7
AD8310 / AD8310ACHIPS
AD8310 / AD8310ARMZ
AD8310 / AD8310ARMZ-REEL7
AD8335 / AD8335ACPZ
AD8335 / AD8335ACPZ-REEL
AD8335 / AD8335ACPZ-REEL7
AD8336 / AD8336ACPZ-R7
AD8336 / AD8336ACPZ-RL
AD8336 / AD8336ACPZ-WP
AD8337 / AD8337BCPZ-REEL
AD8337 / AD8337BCPZ-REEL7
AD8337 / AD8337BCPZ-WP
AD8397 / AD45257ACPZ-R7
AD8397 / AD8397ARDZ
AD8397 / AD8397ARDZ-REEL
AD8397 / AD8397ARDZ-REEL7
AD8397 / AD8397ARZ
AD8397 / AD8397ARZ-REEL
AD8397 / AD8397ARZ-REEL7
AD8476 / AD8476ACPZ-R7
AD8476 / AD8476ACPZ-RL
AD8476 / AD8476ACPZ-WP
AD8476 / AD8476ARMZ
AD8476 / AD8476ARMZ-R7
AD8476 / AD8476ARMZ-RL
AD8476 / AD8476BCPZ-R7
AD8476 / AD8476BCPZ-RL
AD8476 / AD8476BCPZ-WP
AD8476 / AD8476BRMZ
AD8476 / AD8476BRMZ-R7
AD8476 / AD8476BRMZ-RL
AD8610 / AD8610ARMZ-R7
AD8610 / AD8610ARMZ-REEL
AD8610 / AD8610ARZ
AD8610 / AD8610ARZ-REEL
AD8610 / AD8610ARZ-REEL7
AD8610 / AD8610BRZ
AD8610 / AD8610BRZ-REEL
AD8610 / AD8610BRZ-REEL7
AD8614 / AD8614ARTZ-REEL7
AD8620 / AD8620ARZ
AD8620 / AD8620ARZ-REEL
AD8620 / AD8620ARZ-REEL7
AD8620 / AD8620BRZ
AD8620 / AD8620BRZ-REEL7
AD8626 / AD8626ARMZ
AD8626 / AD8626ARMZ-REEL
AD8626 / AD8626ARZ
AD8626 / AD8626ARZ-REEL
AD8626 / AD8626ARZ-REEL7
AD8627 / AD8627AKSZ-R2
AD8627 / AD8627AKSZ-REEL
AD8627 / AD8627AKSZ-REEL7
AD8627 / AD8627ARZ
AD8627 / AD8627ARZ-REEL
AD8627 / AD8627ARZ-REEL7
AD8641 / AD8641AKSZ-R2
AD8641 / AD8641AKSZ-REEL7
AD8641 / AD8641ARZ
AD8641 / AD8641ARZ-REEL7
AD8641 / ADW60031ARZ-R7
AD8642 / AD8642ARMZ
AD8642 / AD8642ARMZ-REEL
AD8642 / AD8642ARZ
AD8642 / AD8642ARZ-REEL
AD8642 / AD8642ARZ-REEL7
AD8642 / ADW60013ARZ-RL
AD8644 / AD8644ARUZ
AD8644 / AD8644ARUZ-REEL
AD8644 / AD8644ARZ
AD8644 / AD8644ARZ-REEL7
ADA4310-1 / ADA4310-1ACPZ-R7
ADA4310-1 / ADA4310-1ARHZ
ADA4310-1 / ADA4310-1ARHZ-R7
ADA4310-1 / ADA4310-1ARHZ-RL
ADA4311-1 / AD89016ARHZ-R7
ADA4311-1 / ADA4311-1ARHZ
ADA4311-1 / ADA4311-1ARHZ-R7
ADA4410-6 / ADA4410-6ACPZ-R7
ADA4410-6 / ADA4410-6ACPZ-RL
ADA4430-1 / ADA4430-1WYRTZ-R7
ADA4430-1 / ADA4430-1YKSZ-R7
ADA4800 / ADA4800-KGD-WP
ADA4800 / ADA4800ACPZ-R7
ADA4800 / ADA4800ACPZ-RL
ADA4800 / ADA4800X-WP
ADA4817-1 / ADA4817-1ACPZ-R7
ADA4817-1 / ADA4817-1ACPZ-RL
ADA4817-1 / ADA4817-1ARDZ
ADA4817-1 / ADA4817-1ARDZ-R7
ADA4817-1 / ADA4817-1ARDZ-RL
ADA4817-2 / ADA4817-2ACPZ-R7
ADA4817-2 / ADA4817-2ACPZ-RL
ADA4841-1 / ADA4841-1YRJZ-R2
ADA4841-1 / ADA4841-1YRJZ-R7
ADA4841-1 / ADA4841-1YRZ
ADA4841-1 / ADA4841-1YRZ-R7
ADA4841-1 / ADA4841-1YRZ-RL
ADA4841-2 / AD45250-RL
ADA4841-2 / ADA4841-2KGD-PT
ADA4841-2 / ADA4841-2KGD-WP
ADA4841-2 / ADA4841-2YCPZ-R7
ADA4841-2 / ADA4841-2YCPZ-RL
ADA4841-2 / ADA4841-2YRMZ
ADA4841-2 / ADA4841-2YRMZ-R7
ADA4841-2 / ADA4841-2YRMZ-RL
ADA4841-2 / ADA4841-2YRZ
ADA4841-2 / ADA4841-2YRZ-R7
ADA4841-2 / ADA4841-2YRZ-RL
ADA4851-1 / ADA4851-1WYRJZ-R7
ADA4851-1 / ADA4851-1YRJZ-RL7
ADA4851-2 / AD45246-RL
ADA4851-2 / ADA4851-2WYRMZ-R7
ADA4851-2 / ADA4851-2YRMZ
ADA4851-2 / ADA4851-2YRMZ-RL
ADA4851-2 / ADA4851-2YRMZ-RL7
ADA4851-2 / ADW13001Z
ADA4851-4 / AD45104YRUZ-RL
ADA4851-4 / AD80198Z
ADA4851-4 / ADA4851-4WYRUZ-R7
ADA4851-4 / ADA4851-4YRUZ
ADA4851-4 / ADA4851-4YRUZ-RL
ADA4851-4 / ADA4851-4YRUZ-RL7
ADA4851-4 / ADW13005Z
ADA4858-3 / ADA4858-3ACPZ-R7
ADA4858-3 / ADA4858-3ACPZ-RL
ADA4859-3 / ADA4859-3ACPZ-R7
ADA4861-3 / ADA4861-3YRZ
ADA4861-3 / ADA4861-3YRZ-RL7
ADA4862-3 / ADA4862-3YRZ
ADA4862-3 / ADA4862-3YRZ-RL
ADA4862-3 / ADA4862-3YRZ-RL7
ADA4899-1 / AD45260-R7
ADA4899-1 / ADA4899-1YCPZ-R7
ADA4899-1 / ADA4899-1YRDZ
ADA4899-1 / ADA4899-1YRDZ-R7
ADA4899-1 / ADA4899-1YRDZ-RL
ADA4941-1 / ADA4941-1YCPZ-R2
ADA4941-1 / ADA4941-1YCPZ-R7
ADA4941-1 / ADA4941-1YCPZ-RL
ADA4941-1 / ADA4941-1YRZ
ADA4941-1 / ADA4941-1YRZ-R7
ADA4941-1 / ADA4941-1YRZ-RL
ADL5303 / ADL5303ACPZ-R2
ADL5303 / ADL5303ACPZ-R7
ADL5303 / ADL5303ACPZ-RL
ADL5304 / ADL5304ACPZ-R2

Appendix B - Revision History:			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	16-Feb-2026	21-May-2026	Initial Release.



Reliability Report

Report Title: Qualification of ADI Limerick Wafer Fab XF26/18/12/8 Processes for AEC Grade 1 and Non-Automotive Products

Report Number: 25154

Revision: B

Date: 10 Feb 2026

Summary

This report documents the reliability qualification requirements for the release of the XF26/18/12/8 Processes at Analog Devices Limerick Wafer Fabrication Facility. The products listed below were selected to cover the technology being released.

The products are:

The AD8028 is a high speed amplifier with rail-to-rail input and output that operate on low supply voltages and optimized for high performance and a wide dynamic signal range. The AD8028 has low noise (4.3 nV/√Hz, 1.6 pA/√Hz) and low distortion (120 dBc at 1 MHz). The AD8028 is an Automotive Grade 1 product.

The AD8130 is a differential-to-single-ended amplifier with extremely high CMRR at high frequency. The AD8130 is designed as receiver for the transmission of high speed signals over twisted-pair cables to work with the AD8131 or AD8132 drivers.

The AD8304 is a monolithic logarithmic detector optimized for the measurement of low frequency signal power in fiber optic systems. It uses an advanced translinear technique to provide an exceptionally large dynamic range in a versatile and easily used form.

AECQ100 Qualification Test Methods and Summary

AEC Test Group	AEC Stress Test Name	Abbreviation	AEC Test#	Reference
Group A ACCELERATED ENVIRONMENT STRESS TESTS	Preconditioning	PC	A1	Table 2, and Table 4
	Temperature Humidity Bias or Biased-HAST	THB or HAST	A2	
	Autoclave or Unbiased HAST or Temperature Humidity (without Bias)	AC, UHST, or TH	A3	
	Temperature Cycle	TC	A4	
	Power Temperature Cycling	PTC	A5	
	High Temperature Storage Life	HTSL	A6	
Group B ACCELERATED LIFETIME SIMULATION TESTS	High Temperature Operating Life	HTOL	B1	Table 2, and Table 4
	Early Life Failure Rate	ELFR	B2	
	NVM Endurance, Data Retention, and Operational Life	EDR	B3	
Group C PACKAGE ASSEMBLY INTEGRITY TESTS	Wire Bond Shear	WBS	C1	• Test C2 (and C1 for Cu Wire) are shown in Table 4. • Tests C3-6 are qualified and controlled with inline monitors and may be viewed on-site at Analog Devices.
	Wire Bond Pull Strength	WBP	C2	
	Solderability	SD	C3	
	Physical Dimensions	PD	C4	
	Solder Ball Shear	SBS	C5	
	Lead Integrity	LI	C6	
Group D DIE FABRICATION RELIABILITY TESTS	Electromigration	EM	D1	Die Fabrication Reliability data may be viewed on-site at Analog Devices.
	Time Dependent Dielectric Breakdown	TDDB	D2	
	Hot Carrier Injection	HCI	D3	
	Negative Bias Temperature Instability	BTI	D4	
	Stress Migration	SM	D5	
Group E ELECTRICAL VERIFICATION TESTS	Pre- and Post-Stress Electrical Test	TEST	E1	Table 5, and Table 6
	Electrostatic Discharge Human Body Model	HBM	E2	
	Electrostatic Discharge Charged Device Model	CDM	E3	
	Latch-Up	LU	E4	
	Electrical Distributions	ED	E5	• For Tests E5, E6 and E7, ADI New Product Yield Analysis Testing Guidelines meet AEC Q100 requirements. • Results for Tests E7-E11 are available as applicable on a case–by-case basis. • Test E12 results may be viewed on-site at Analog Devices
	Fault Grading	FG	E6	
	Characterization	CHAR	E7	
	Electromagnetic Compatibility	EMC	E9	
	Short Circuit Characterization	SC	E10	
	Soft Error Rate	SER	E11	
	Lead (Pb) Free	LF	E12	
Group F DEFECT SCREENING TESTS	Process Average Test	PAT	F1	ADI New Product Yield Analysis Testing Guidelines meet AECQ100 Requirements.
	Statistical Bin/Yield Analysis	SBA	F2	
Group G CAVITY PACKAGE INTEGRITY TESTS	Mechanical Shock	MS	G1	< Applicable only for Cavity-Packages>
	Variable Frequency Vibration	VFV	G2	
	Constant Acceleration	CA	G3	
	Gross/Fine Leak	GFL	G4	
	Package Drop	DROP	G5	
	Lid Torque	LT	G6	
	Die Shear	DS	G7	
	Internal Water Vapor	IWV	G8	

Die/Fab Product Characteristics

Table 1: Die/Fab Product Characteristics- XF26/18/12/8 at ADI Limerick

Product Characteristics	Product(s) to be qualified		
Generic/Root Part #	AD8130	AD8028	AD8304
Die Id	8YZ59 E	8YZ67 C	8YZ68 C
Die Size (mm)	1.095 x 1.405	1.49 x 1.365	1.36 x 1.38
Wafer Fabrication Site	ADI-Limerick	ADI-Limerick	ADI-Limerick
Wafer Fabrication Process	XF26	XF12	XF08
Die Substrate	Si	Si	Si
Metallization / Layers	AlCu(1.0%)/2	AlCu(0.5%)/2	AlCu(0.5%)/2
Polyimide	No	Yes	No
Passivation	doped-oxide/SiN	doped-oxide/SiN	doped-oxide/SiN

Die/Fab Test Results

Table 2.1: Die/Fab Test Results – XF26/18/12/8 at ADI Limerick

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
High Temperature Operating Life (HTOL)[1]	NA	JESD22-A108	125°C<Tj<135°C, Biased, 1,000 Hours	AD8130	Q21210.1.HO1_RES	0/77	R
					Q21210.2.HO2_RES	0/77	R
					Q21210.3.HO3_RES	0/77	R
				AD8304	Q21208.1.HO1_RES	0/77	R
					Q21208.2.HO2_RES	0/77	R
					Q21208.3.H03_RES	0/77	R
	B1		Ta=125°C, Tj=132°C Biased, 1,000 Hours	AD8028	Q21209.1.HO1_RES	0/77	RHC
					Q21209.2.HO2_RES	0/77	RHC
					Q21209.3.H03_RES	0/77	RHC
Early Life Failure Rate (ELFR)	B2	AEC-Q100-008	Ta=125°C, Tj=132°C Biased, 48 Hours	AD8028	Q21209.1.EL1_RES	0/800	RH
					Q21209.2.EL2_RES	0/800	RH
					Q21209.3.EL3_RES	0/800	RH
High Temperature Storage Life (HTSL)	NA	JESD22-A103	150°C, 1,000 Hours	AD8130	Q21210.1.HS1_RES	0/77	R
				AD8304	Q21208.1.HS1_RES	0/77	R
	A6			AD8028	Q21209.1.HS1_RES	0/45	RH
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	NA	JESD22-A110	130C 85%RH 33.3 psia, Biased, 96 Hours	AD8304	Q21208.1.HA1_RES_130C	0/77	R
					Q21208.2.HA2_RES	0/77	R
					Q21208.3.HA3_RES	0/77	R
	A2			AD8028	Q21209.1.HA1_RES	0/77	RH
					Q21209.2.HA2_RES	0/77	RH
					Q21209.3.HA3_RES	0/77	RH
	NA		110C 85%RH 17.7 psia, Biased, 264 Hours	AD8130	Q21210.1.HA1_RES	0/77	R
					Q21210.2.HA2_RES	0/77	R
					Q21210.3.HA3_RES	0/77	R

Unbiased HAST (UHST)[1]	NA	JESD22-A118	130C 85%RH 33.3 psia, Biased, 96 Hours	AD8304	Q21208.1.UH1_RES	0/77	R
					Q21208.2.UH2_RES	0/77	R
					Q21208.3.UH3_RES	0/77	R
	A3			AD8028	Q21209.1.UH1_RES	0/77	R
					Q21209.2.UH2_RES	0/77	R
					Q21209.3.UH3_RES	0/77	R
	NA		110C 85%RH 17.7 psia, Biased, 264 Hours	AD8130	Q21210.1.UH1_RES	0/77	R
					Q21210.2.UH2_RES	0/77	R
					Q21210.3.UH3_RES	0/77	R
Temperature Cycling (TC)[1]	NA	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8304	Q21208.1.TC1_RES	0/77	R
					Q21208.2.TC2_RES	0/77	R
					Q21208.3.TC3_RES	0/77	R
	A4			AD8028	Q21209.1.TC1_RES	0/77	RH
					Q21209.2.TC2_RES	0/77	RH
					Q21209.3.TC3_RES	0/77	RH
	NA			AD8130	Q21210.1.TC1_RES	0/77	R
					Q21210.2.TC2_RES	0/77	R
					Q21210.3.TC3_RES	0/77	R

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

Package/Assembly Product Characteristics

Table 3.1: Package/Assembly Product Characteristics - 10-MINI_SO at CARSEM (CRM)

Product Characteristics	Product(s) to be qualified
Generic/Root Part #	AD8028
Package	10-MINI_SO
Body Size (mm)	3.00 x 3.00 x 0.85
Assembly Location	CARSEM (CRM)
MSL/Peak Reflow Temperature(°C)	1 / 260°C
Mold Compound	Hitachi CEL 8240HF10LXC
Die Attach/Underfill/TIM	Hysol QMI 519 conductive
Leadframe Material	Copper
Lead Finish	100 Sn
Wire Bond Material/Diameter (mils)	Tanaka GLD 4N Gold / 1.0

Table 3.2: Package/Assembly Product Characteristics - 8-SOIC_N at JCET (JC2)

Product Characteristics	Product(s) to be qualified
Generic/Root Part #	AD8130
Package	8-SOIC_N
Body Size (mm)	3.00 x 3.00 x 0.85
Assembly Location	JCET (JC2)
MSL/Peak Reflow Temperature(°C)	1 / 260°C
Mold Compound	Sumitomo EME-G600F-B
Die Attach/Underfill/TIM	Ablestik 8290
Leadframe Material	Copper
Lead Finish	100 Sn
Wire Bond Material/Diameter (mils)	Heraeus, HA6, 4N / 1.20

Table 3.3: Package/Assembly Product Characteristics - 14-TSSOP_4.4 at AMKOR (AP1)

Product Characteristics	Product(s) to be qualified
Generic/Root Part #	AD8304
Package	14-TSSOP_4.4
Body Size (mm)	5.00 x 4.40 x 1.00
Assembly Location	AMKOR (AP1)
MSL/Peak Reflow Temperature(°C)	1 / 260°C
Mold Compound	Sumitomo G700K
Die Attach	Ablestik 8290 conductive
Leadframe Material	Copper
Lead Finish	100 Sn
Wire Bond Material/Diameter (mils)	Gold / 1.00

Package/Assembly Test Results

Table 4.1: Package/Assembly Test Results - 10-MINI_SO at CARSEM (CRM)

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
Solder Heat Resistance (SHR)	A1	J-STD-020	MSL-1	AD8028	Q21209.1.SH1_RES	0/11	R
					Q21209.2.SH2_RES	0/11	R
					Q21209.3.SH3_RES	0/11	R
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	A2	JESD22-A110	130°C 85%RH 33.3 psia, Biased, 96 Hours	AD8028	Q21209.1.HA1_RES	0/77	RH
					Q21209.2.HA2_RES	0/77	RH
					Q21209.3.HA3_RES	0/77	RH
Unbiased HAST (UHST) [1]	A3	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8028	Q21209.1.UH1_RES	0/77	R
					Q21209.2.UH2_RES	0/77	R
					Q21209.3.UH3_RES	0/77	R
Temperature Cycling (TC)[1]	A4	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8028	Q21209.1.TC1_RES	0/77	RH
					Q21209.2.TC2_RES	0/77	RH
					Q21209.3.TC3_RES	0/77	RH
High Temperature Storage Life (HTSL)	A6	JESD22-A103	150°C, 1,000 Hours	AD8028	Q21209.1.HS1_RES	0/45	RH
Wire Bond Pull – Post TC	C2	AEC- Q001	3 gF	AD8028	Q21209.1.WPT	0/5	NA

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

Table 4.2: Package/Assembly Test Results - 8-SOIC_N at JCET (JC2)

Test Name	AEC #	Spec	Conditions	Generic / Root Part #	Lot #	Fail/SS	eTest Temp
Solder Heat Resistance (SHR)	NA	J-STD-020	MSL-1	AD8130	Q21210.1.SH1_RES	0/11	R
					Q21210.2.SH2_RES	0/11	R
					Q21210.3.SH3_RES	0/11	R
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	NA	JESD22-A110	110°C 85%RH 17.7 psia, Biased, 96 Hours	AD8130	Q21210.1.HA1_RES	0/77	R
					Q21210.2.HA2_RES	0/77	R
					Q21210.3.HA3_RES	0/77	R
Unbiased HAST (UHST)[1]	NA	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8130	Q21210.1.UH1_RES	0/77	R
					Q21210.2.UH2_RES	0/77	R
					Q21210.3.UH3_RES	0/77	R
Temperature Cycling (TC)[1]	NA	JESD22-A104	-65°C/+150°C, 1000 Cycles	AD8130	Q21210.1.TC1_RES	0/77	R
					Q21210.2.TC2_RES	0/77	R
					Q21210.3.TC3_RES	0/77	R
High Temperature Storage Life (HTSL)	NA	JESD22-A103	150°C, 1,000 Hours	AD8130	Q21210.1.HS1_RES	0/77	R

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

Table 4.3: Package/Assembly Test Results - 14-TSSOP_4.4 at AMKOR (AP1)

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
Solder Heat Resistance (SHR)	NA	J-STD-020	MSL-1	AD8304	Q21208.1.SH1_RES	0/11	R
					Q21208.2.SH2_RES	0/11	R
					Q21208.3.SH3_RES	0/11	R
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	NA	JESD22-A110	130°C 85%RH 33.3 psia, Biased, 96 Hours	AD8304	Q21208.1.HA1_RES_130C	0/77	R
					Q21208.2.HA2_RES	0/77	R
					Q21208.3.HA3_RES	0/77	R
Unbiased HAST (UHST)[1]	NA	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8304	Q21208.1.UH1_RES	0/77	R
					Q21208.2.UH2_RES	0/77	R
					Q21208.3.UH3_RES	0/77	R
Temperature Cycling (TC)[1]	NA	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8304	Q21208.1.TC1_RES	0/77	R
					Q21208.2.TC2_RES	0/77	R
					Q21208.3.TC3_RES	0/77	R
High Temperature Storage Life (HTSL)	NA	JESD22-A103	150°C, 1,000 Hours	AD8304	Q21208.1.HS1_RES	0/77	R

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

ESD and Latch-Up Test Results

Table 5: ESD Test Result

ESD Model	Generic/Root Part #	Package	ESD Test Spec	RC Network	Highest Pass Level	Class	eTest Temp
FICDM	AD8130	SOIC_N	JS-002	1Ω, Cpkg	±2000V	C3	R
	AD8304	TSSOP_4.4			±1500V	C3	R
	AD8028	MINI_SO	AEC Q100-011		±1250V	C3	RH
HBM	AD8130	SOIC_N	JS-001	1.5kΩ, 100pF	±1500V	1C	R
	AD8304	TSSOP_4.4			±1500V	1C	R
	AD8028	MINI_SO	AEC Q100-002		±8000V	3B	RH

Table 6: Latch Up Test Result

LU Test Spec	Generic/Root Part #	Passing Current	Passing Over-Voltage	Temperature (T_A)	Class	eTest Temp
JESD78	AD8028	+100mA, -100mA	+12.0V	125°C	IIA	RH

Approvals

Reliability Engineer: